

Atty. Docket No. CPAC 1017-5
Appl. No. 10/632,552

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS)

Application No.: 10/632,552)

Filed: August 2, 2003)

Title: **Semiconductor multi-package module having)
package stacked over die-up flip chip)
ball grid array package and having wire)
bond interconnect between stacked packages)**

Examiner: Chris C. Chu

Group Art Unit: 2815

Date: January 10, 2004

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CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being sent by facsimile to:
Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, at the
Central Fax No. 703 872-9306 on January 10, 2005.

Signed


Paula Faulk Hurley

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed October 08, 2004, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the **Listing of Claims** which begins on page 5 of this paper.

Remarks begin on page 9 of this paper.